



- NOTES:
- MATERIAL:
    - HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0;
    - CONTACT: COPPER ALLOY
  - FINISH:
    - CONTACT:
      - 50u" MIN. NICKEL UNDERPLATING OVER ALL,
      - 80~120u" MIN. PURE TIN PLATING OVER ALL.
  - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
  - SPEC. PLS. REFER TO PS-50323-xxxx-xxx
  - PACKAGE PLS. REFER TO 87343-xxx-TRP/87343-xxx-C-TRP
  - PART NUMBER

50325-XXX X X-XXX

NO OF CKT

Others	Housing color	HALOGEN FREE	DIM D
001	BLACK	HF	1.5
002	BLACK	HF	2.2
003	WHITE	HF	2.2
004	BLACK	HF	3.2

Packing

4:T&R WITH MYLAR  
5:TUBE WITH MYLAR  
7:T&R WITH COVER  
8:TUBE WITH COVER

PLATING :

L:PURE TIN (BRIGHT)  
N:MATT TIN

CKT	DIM A	DIM B	DIM C
2	2.5	5.4	7.5
3	5.0	7.9	10.0
4	7.5	10.4	12.5
5	10.0	12.9	15.0
6	12.5	15.4	17.5
7	15.0	17.9	20.0
8	17.5	20.4	22.5
9	20.0	22.9	25.0
10	22.5	25.4	27.5
11	25.0	27.9	30.0
12	27.5	30.4	32.5
13	30.0	32.9	35.0
14	32.5	35.4	37.5
15	35.0	37.9	40.0

QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓢ GENERAL TOLERANCES ( UNLESS SPECIFIED ) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY SHISONGTAO	DATE 20/05/19		
	CHECKED BY XUZHUYONG	DATE 20/05/19		TITLE 2.5mm W-T-B WAFER S/T T/H TYPE
	UNITS mm		SIZE A4	RFG NO. N/A
	SCALE 5:1	SHEET NO. 1 OF 1	REV D	DWG NO. 50325-XXXXX-XXX